



**COMPLEMENTARY DUAL 20V LOW SATURATION TRANSISTORS** 

### **Features and Benefits**

#### NPN Transistor

- $BV_{CEO} > 20V$
- I<sub>C</sub> = 4.5A Continuous Collector Current
- Low Saturation Voltage (150mV max @ 1A) .
- $R_{SAT} = 47m\Omega$  for a low equivalent On-Resistance •

**PNP** Transistor

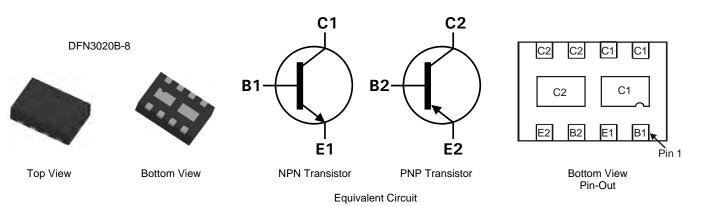
- $BV_{CEO} > -20V$ •
- I<sub>C</sub> = -3.5A Continuous Collector Current ٠
- Low Saturation Voltage (-220mV max @ -1A) ٠
- $R_{SAT} = 64m\Omega$  for a low equivalent On-Resistance
- hFE characterized up to 6A for high current gain hold up
- Low profile 0.8mm high package for thin applications
- $R_{\theta JA}$  efficient, 40% lower than SOT26
- 6mm<sup>2</sup> footprint, 50% smaller than TSOP6 and SOT26
- Lead-Free, RoHS Compliant (Note 1)
- Halogen and Antimony Free. "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

## **Mechanical Data**

- Case: DFN3020B-8
- Case material: Molded Plastic. "Green" Molding Compound.
- Terminals: Pre-Plated NiPdAu leadframe.
- Nominal package height: 0.8mm
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Weight: 0.013 grams (approximate)

### **Applications**

- DC DC Converters
- Charging circuits
- Power switches
- Motor control
- LED Backlighting circuits
- Portable applications



### **Ordering Information**

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTC6718MCTA	DB2	7	8	3000

Notes: 1. No purposefully added lead.

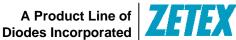
2. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com

## **Marking Information**



DB2 = Product type marking code Top view, dot denotes pin 1





## **Maximum Ratings** @ $T_A = 25^{\circ}C$ unless otherwise specified

Characterist	Symbol	NPN	PNP	Unit	
Collector-Base Voltage		V <sub>CBO</sub>	40	-25	V
Collector-Emitter Voltage		V <sub>CEO</sub>	20	-20	V
Emitter-Base Voltage		V <sub>EBO</sub>	7	-7	V
Peak Pulse Current		Ісм	12	-6	А
Continuous Collector Current         (Notes 3 & 6)           Continuous Collector Current         (Notes 4 & 6)		Ι <sub>C</sub>	4.5	-3.5	٥
			5	-3.8	A
Base Current		I <sub>B</sub>		1	A

### Thermal Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	NPN	PNP	Unit	
	(Notes 3 & 6)		1.5 12 2.45 19.6 1.13 8 1.7 13.6		W mW/°C
Power Dissipation	(Notes 4 & 6)				
Linear Derating Factor	(Notes 5 & 6)	P <sub>D</sub>			
	(Notes 5 & 7)				
	(Notes 3 & 6)		83.3 51.0 111 73.5		°C/W
Thermal Desistance, lunction to Ambient	(Notes 4 & 6)				
Thermal Resistance, Junction to Ambient	(Notes 5 & 6)	R <sub>θJA</sub>			
	(Notes 5 & 7)				
Thermal Resistance, Junction to Lead (Notes 6 & 8)		R <sub>θJL</sub>	17.1		
Operating and Storage Temperature Range	-	TJ, TSTG	-55 to +150		°C

3. For a dual device surface mounted on 28mm x 28mm (8cm<sup>2</sup>) FR4 PCB with high coverage of single sided 2 oz copper, in still air conditions; the device is Notes: measured when operating in a steady-state condition. The heatsink is split in half with the exposed collector pads connected to each half.

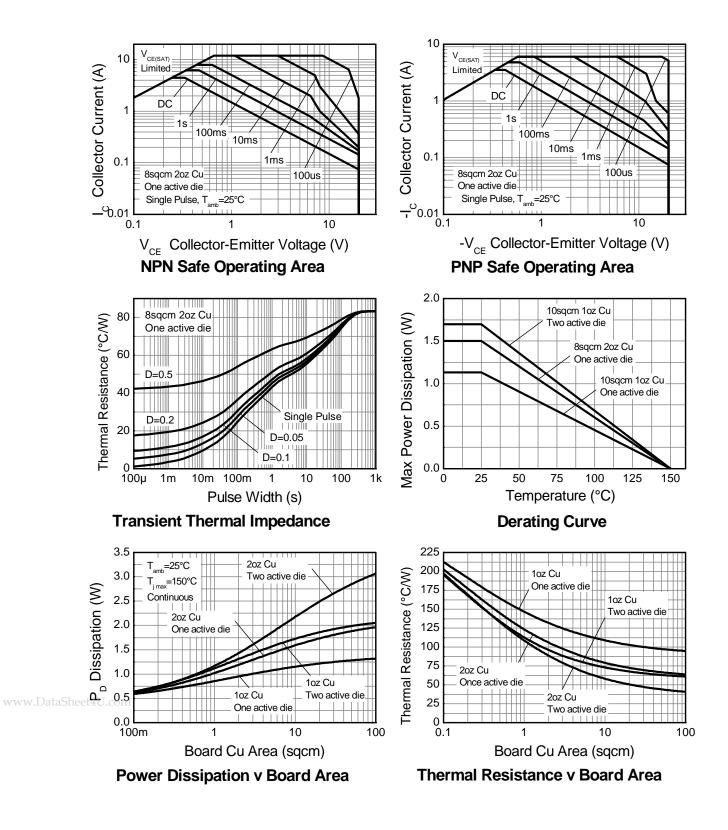
4. Same as note (3), except the device is measured at t <5 sec.</li>
5. Same as note (3), except the device is surface mounted on 31mm x 31mm (10cm<sup>2</sup>) FR4 PCB with high coverage of single sided 1oz copper.
6. For a dual device with 2 active die running at equal power.

8. Thermal resistance from junction to solder-point (at the end of the collector lead).





# **Thermal Characteristics**



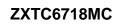


## NPN - Electrical Characteristics @ T<sub>A</sub> = 25°C unless otherwise specified

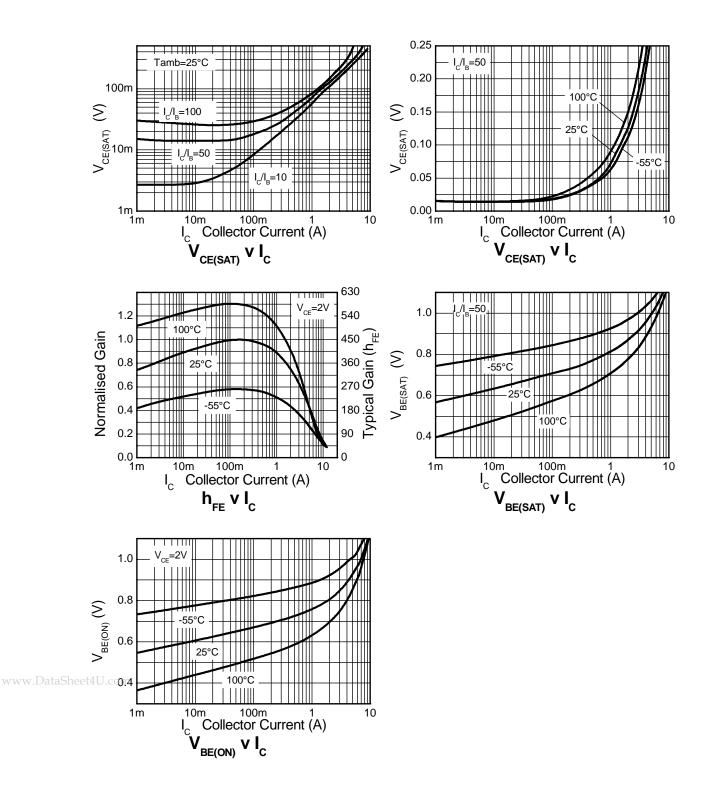
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	40	100	-	V	I <sub>C</sub> = 100μA
Collector-Emitter Breakdown Voltage (Note 9)	BV <sub>CEO</sub>	20	27	-	V	I <sub>C</sub> = 10mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	7	8.2	-	V	I <sub>E</sub> = 100μA
Collector Cutoff Current	I <sub>CBO</sub>	-	-	100	nA	$V_{CB} = 30V$
Emitter Cutoff Current	I <sub>EBO</sub>	-	-	100	_ nA	$V_{EB} = 6V$
Collector Emitter Cutoff Current	ICES	-	-	100	nA	V <sub>CE</sub> = 16V
		200	400	-	-	I <sub>C</sub> = 10mA, V <sub>CE</sub> = 2V
Static Forward Current Transfer Ratio	h	300	450	-	-	$I_{C} = 200 \text{mA}, V_{CE} = 2 \text{V}$
(Note 9)	h <sub>FE</sub>	200	360	-	-	$I_{C} = 2A, V_{CE} = 2V$
		100	180	-	-	$I_{C} = 6A, V_{CE} = 2V$
	V <sub>CE(sat)</sub>		8	15	mV	$I_{\rm C} = 0.1 {\rm A}, I_{\rm B} = 10 {\rm mA}$
O alla atam Englithan O atamatikan Malka ma			90	150		$I_{C} = 1A, I_{B} = 10mA$
Collector-Emitter Saturation Voltage		-	115	135		$I_{C} = 2A, I_{B} = 50mA$
(Note 9)			190	250		$I_{\rm C} = 3A, I_{\rm B} = 100 \text{mA}$
			210	300		$I_{\rm C} = 4.5 \text{A}, I_{\rm B} = 125 \text{mA}$
Base-Emitter Turn-On Voltage (Note 9)	V <sub>BE(on)</sub>	-	0.88	0.97	V	I <sub>C</sub> = 4.5A, V <sub>CE</sub> = 2V
Base-Emitter Saturation Voltage (Note 9)	V <sub>BE(sat)</sub>	-	0.98	1.07	V	I <sub>C</sub> = 4.5A, I <sub>B</sub> = 125mA
Output Capacitance	C <sub>obo</sub>	-	23	30	pF	$V_{CB} = 10V, f = 1MHz$
Transition Frequency	f <sub>T</sub>	100	140	-	MHz	$V_{CE} = 10V, I_C = 50mA, f = 100MHz$
Turn-on Time	t <sub>on</sub>	-	170	-	ns	$V_{CC} = 10V, I_{C} = 3A$
Turn-off Time	t <sub>off</sub>	-	400	-	ns	$I_{B1} = I_{B2} = 10 \text{mA}$

Notes: 9. Measured under pulsed conditions. Pulse width  $\leq$  300µs. Duty cycle  $\leq$  2%.





# **NPN - Typical Electrical Characteristics**





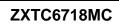


## PNP - Electrical Characteristics @TA = 25°C unless otherwise specified

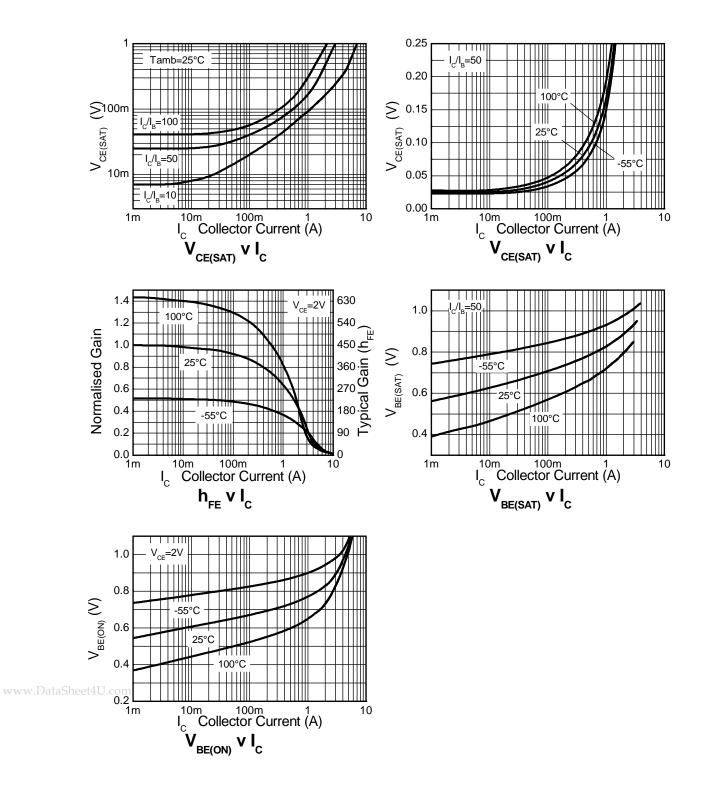
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-25	-35	-	V	I <sub>C</sub> = -100μA
Collector-Emitter Breakdown Voltage (Note 10)	BV <sub>CEO</sub>	-20	-25	-	V	I <sub>C</sub> = -10mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-7	-8.5	-	V	I <sub>E</sub> = -100μA
Collector Cutoff Current	I <sub>CBO</sub>	-	-	-100	nA	V <sub>CB</sub> = -20V
Emitter Cutoff Current	I <sub>EBO</sub>	-	-	-100	. nA	$V_{EB} = -6V$
Collector Emitter Cutoff Current	ICES	-	-	-100	nA	V <sub>CES</sub> = -16V
Static Forward Current Transfer Ratio (Note 10)	h <sub>FE</sub>	300 300 150 15	475 450 230 30	- - -	-	$\begin{split} I_{C} &= -10 \text{mA}, \ V_{CE} &= -2 \text{V} \\ I_{C} &= -100 \text{mA}, \ V_{CE} &= -2 \text{V} \\ I_{C} &= -2 \text{A}, \ V_{CE} &= -2 \text{V} \\ I_{C} &= -6 \text{A}, \ V_{CE} &= -2 \text{V} \end{split}$
Collector-Emitter Saturation Voltage (Note 10)	V <sub>CE(sat)</sub>	- - - -	-19 -170 -190 -240 -225	-30 -220 -250 -350 -300	mV	$\begin{split} I_{C} &= -0.1A, \ I_{B} &= -10 mA \\ I_{C} &= -1A, \ I_{B} &= -20 mA \\ I_{C} &= -1.5A, \ I_{B} &= -50 mA \\ I_{C} &= -2.5A, \ I_{B} &= -150 mA \\ I_{C} &= -3.5A, \ I_{B} &= -350 mA \end{split}$
Base-Emitter Turn-On Voltage (Note 10)	V <sub>BE(on)</sub>	-	-0.87	-0.95	V	I <sub>C</sub> = -3.5A, V <sub>CE</sub> = -2V
Base-Emitter Saturation Voltage (Note 10)	V <sub>BE(sat)</sub>	-	-1.01	-1.12	V	I <sub>C</sub> = -3.5A, I <sub>B</sub> = -350mA
Output Capacitance	C <sub>obo</sub>	-	21	30	pF	V <sub>CB</sub> = -10V. f = 1MHz
Transition Frequency	f <sub>T</sub>	150	180	-	MHz	V <sub>CE</sub> = -10V, I <sub>C</sub> = -50mA, f = 100MHz
Turn-on Time	t <sub>on</sub>	-	40	-	ns	$V_{CC} = -10V, I_C = -1A$
Turn-off Time	t <sub>off</sub>	-	670	-	ns	$I_{B1} = I_{B2} = -10mA$

Notes: 10. Measured under pulsed conditions. Pulse width  $\leq$  300µs. Duty cycle  $\leq$  2%.





# **PNP - Typical Electrical Characteristics**

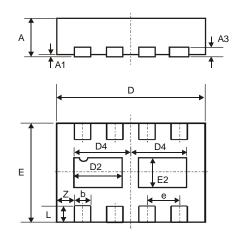






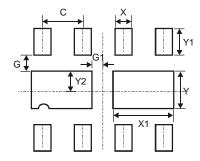
ΙX

## **Package Outline Dimensions**



	DFN3	020B-8	
Dim	Min	Max	Тур
Α	0.77	0.83	0.80
A1	0	0.05	0.02
A3	-	-	0.15
b	0.25	0.35	0.30
D	2.95	3.075	3.00
D2	0.82	1.02	0.92
D4	1.01	1.21	1.11
е	-	-	0.65
Е	1.95	2.075	2.00
E2	0.43	0.63	0.53
L	0.25	0.35	0.30
Ζ	-	-	0.375
All I	Dimens	sions ir	n mm

# Suggested Pad Layout



Dimensions	Value (in mm)			
С	0.650			
G	0.285			
G1	0.090			
Х	0.400			
X1	1.120			
Y	0.730			
Y1	0.500			
Y2	0.365			



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